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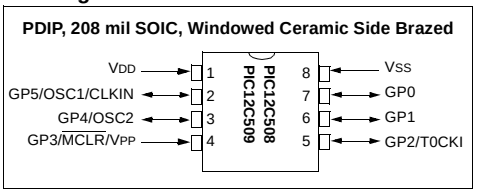
"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

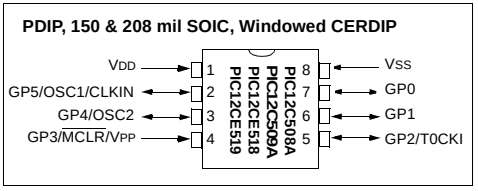
Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	4MHz
Connectivity	-
Peripherals	POR, WDT
Number of I/O	5
Program Memory Size	1.5KB (1K x 12)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	41 x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 5.5V
Data Converters	-
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	8-SOIC (0.209", 5.30mm Width)
Supplier Device Package	8-SOIJ
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic12c509at-04e-sm

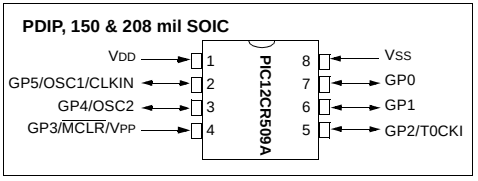
Pin Diagram - PIC12C508/509



Pin Diagram - PIC12C508A/509A, PIC12CE518/519



Pin Diagram - PIC12CR509A



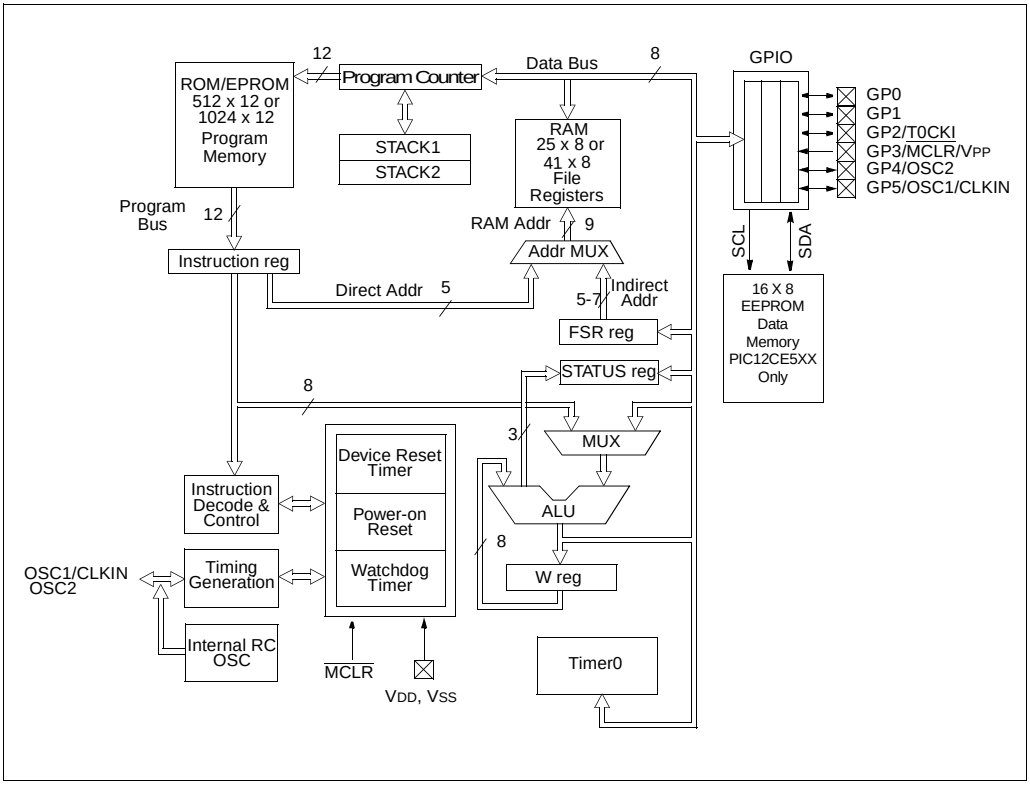
Device Differences

Device	Voltage Range	Oscillator	Oscillator Calibration[2] (Bits)	Process Technology (Microns)
PIC12C508A	3.0-5.5	See Note 1	6	0.7
PIC12LC508A	2.5-5.5	See Note 1	6	0.7
PIC12C508	2.5-5.5	See Note 1	4	0.9
PIC12C509A	3.0-5.5	See Note 1	6	0.7
PIC12LC509A	2.5-5.5	See Note 1	6	0.7
PIC12C509	2.5-5.5	See Note 1	4	0.9
PIC12CR509A	2.5-5.5	See Note 1	6	0.7
PIC12CE518	3.0-5.5	-	6	0.7
PIC12LCE518	2.5-5.5	-	6	0.7
PIC12CE519	3.0-5.5	-	6	0.7
PIC12LCE519	2.5-5.5	-	6	0.7

Note 1: If you change from the PIC12C50X to the PIC12C50XA or to the PIC12CR50XA, please verify oscillator characteristics in your application.

Note 2: See Section 7.2.5 for OSCCAL implementation differences.

FIGURE 3-1: PIC12C5XX BLOCK DIAGRAM



6.1 Using Timer0 with an External Clock

When an external clock input is used for Timer0, it must meet certain requirements. The external clock requirement is due to internal phase clock (TOSC) synchronization. Also, there is a delay in the actual incrementing of Timer0 after synchronization.

6.1.1 EXTERNAL CLOCK SYNCHRONIZATION

When no prescaler is used, the external clock input is the same as the prescaler output. The synchronization of T0CKI with the internal phase clocks is accomplished by sampling the prescaler output on the Q2 and Q4 cycles of the internal phase clocks (Figure 6-4). Therefore, it is necessary for T0CKI to be high for at least 2TOSC (and a small RC delay of 20 ns) and low for at least 2TOSC (and a small RC delay of 20 ns). Refer to the electrical specification of the desired device.

When a prescaler is used, the external clock input is divided by the asynchronous ripple counter-type prescaler so that the prescaler output is symmetrical. For the external clock to meet the sampling requirement, the ripple counter must be taken into account. Therefore, it is necessary for T0CKI to have a period of at least 4TOSC (and a small RC delay of 40 ns) divided by the prescaler value. The only requirement on T0CKI high and low time is that they do not violate the minimum pulse width requirement of 10 ns. Refer to parameters 40, 41 and 42 in the electrical specification of the desired device.

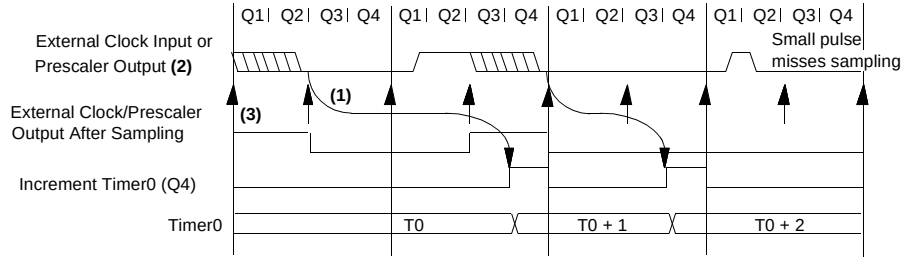
6.1.2 TIMER0 INCREMENT DELAY

Since the prescaler output is synchronized with the internal clocks, there is a small delay from the time the external clock edge occurs to the time the Timer0 module is actually incremented. Figure 6-4 shows the delay from the external clock edge to the timer incrementing.

6.1.3 OPTION REGISTER EFFECT ON GP2 TRIS

If the option register is set to read TIMER0 from the pin, the port is forced to an input regardless of the TRIS register setting.

FIGURE 6-4: TIMER0 TIMING WITH EXTERNAL CLOCK



Note 1: Delay from clock input change to Timer0 increment is 3Tosc to 7Tosc. (Duration of Q = Tosc). Therefore, the error in measuring the interval between two edges on Timer0 input = ± 4Tosc max.
2: External clock if no prescaler selected, Prescaler output otherwise.
3: The arrows indicate the points in time where sampling occurs.

8.2.3 EXTERNAL CRYSTAL OSCILLATOR CIRCUIT

Either a prepackaged oscillator or a simple oscillator circuit with TTL gates can be used as an external crystal oscillator circuit. Prepackaged oscillators provide a wide operating range and better stability. A well-designed crystal oscillator will provide good performance with TTL gates. Two types of crystal oscillator circuits can be used: one with parallel resonance, or one with series resonance.

Figure 8-4 shows implementation of a parallel resonant oscillator circuit. The circuit is designed to use the fundamental frequency of the crystal. The 74AS04 inverter performs the 180-degree phase shift that a parallel oscillator requires. The 4.7 kΩ resistor provides the negative feedback for stability. The 10 kΩ potentiometers bias the 74AS04 in the linear region. This circuit could be used for external oscillator designs.

FIGURE 8-4: EXTERNAL PARALLEL RESONANT CRYSTAL OSCILLATOR CIRCUIT

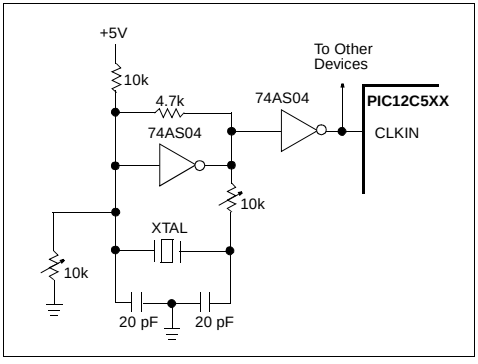
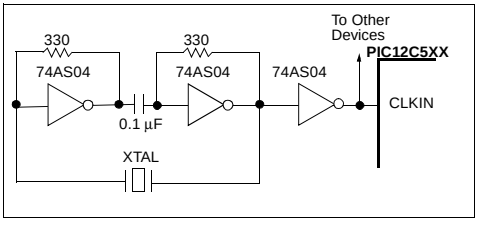


Figure 8-5 shows a series resonant oscillator circuit. This circuit is also designed to use the fundamental frequency of the crystal. The inverter performs a 180-degree phase shift in a series resonant oscillator circuit. The 330 Ω resistors provide the negative feedback to bias the inverters in their linear region.

FIGURE 8-5: EXTERNAL SERIES RESONANT CRYSTAL OSCILLATOR CIRCUIT



8.2.4 EXTERNAL RC OSCILLATOR

For timing insensitive applications, the RC device option offers additional cost savings. The RC oscillator frequency is a function of the supply voltage, the resistor (Rext) and capacitor (Cext) values, and the operating temperature. In addition to this, the oscillator frequency will vary from unit to unit due to normal process parameter variation. Furthermore, the difference in lead frame capacitance between package types will also affect the oscillation frequency, especially for low Cext values. The user also needs to take into account variation due to tolerance of external R and C components used.

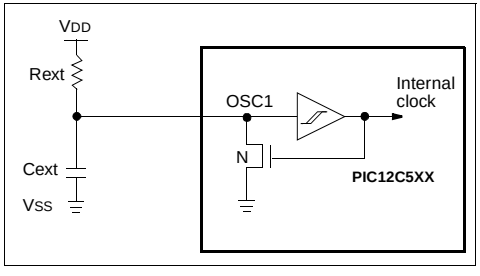
Figure 8-6 shows how the R/C combination is connected to the PIC12C5XX. For Rext values below 2.2 kΩ, the oscillator operation may become unstable, or stop completely. For very high Rext values (e.g., 1 MΩ) the oscillator becomes sensitive to noise, humidity and leakage. Thus, we recommend keeping Rext between 3 kΩ and 100 kΩ.

Although the oscillator will operate with no external capacitor (Cext = 0 pF), we recommend using values above 20 pF for noise and stability reasons. With no or small external capacitance, the oscillation frequency can vary dramatically due to changes in external capacitances, such as PCB trace capacitance or package lead frame capacitance.

The Electrical Specifications sections show RC frequency variation from part to part due to normal process variation. The variation is larger for larger R (since leakage current variation will affect RC frequency more for large R) and for smaller C (since variation of input capacitance will affect RC frequency more).

Also, see the Electrical Specifications sections for variation of oscillator frequency due to V_{DD} for given Rext/Cext values as well as frequency variation due to operating temperature for given R, C, and V_{DD} values.

FIGURE 8-6: EXTERNAL RC OSCILLATOR MODE



8.6.1 WDT PERIOD

The WDT has a nominal time-out period of 18 ms, (with no prescaler). If a longer time-out period is desired, a prescaler with a division ratio of up to 1:128 can be assigned to the WDT (under software control) by writing to the OPTION register. Thus, a time-out period of a nominal 2.3 seconds can be realized. These periods vary with temperature, VDD and part-to-part process variations (see DC specs).

Under worst case conditions (VDD = Min., Temperature = Max., max. WDT prescaler), it may take several seconds before a WDT time-out occurs.

8.6.2 WDT PROGRAMMING CONSIDERATIONS

The CLRWDT instruction clears the WDT and the postscaler, if assigned to the WDT, and prevents it from timing out and generating a device RESET.

The SLEEP instruction resets the WDT and the postscaler, if assigned to the WDT. This gives the maximum SLEEP time before a WDT wake-up reset.

FIGURE 8-12: WATCHDOG TIMER BLOCK DIAGRAM

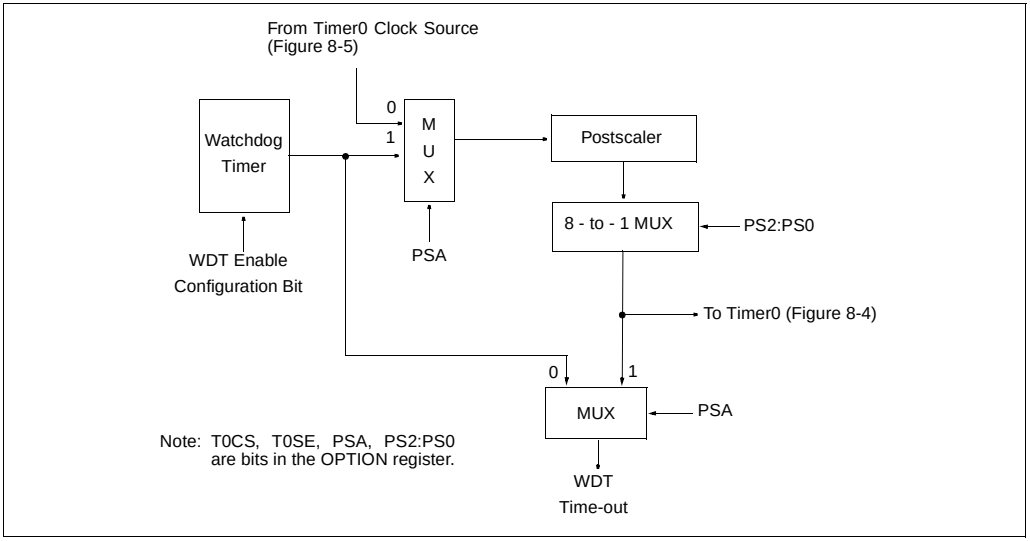


TABLE 8-6: SUMMARY OF REGISTERS ASSOCIATED WITH THE WATCHDOG TIMER

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on Power-On Reset	Value on All Other Resets
N/A	OPTION	$\overline{GPWU}$	$\overline{GPPU}$	T0CS	T0SE	PSA	PS2	PS1	PS0	1111 1111	1111 1111

Legend: Shaded boxes = Not used by Watchdog Timer, – = unimplemented, read as '0', u = unchanged

TABLE 9-2: INSTRUCTION SET SUMMARY

Mnemonic, Operands		Description	Cycles	12-Bit Opcode MSb	LSb	Status Affected	Notes
ADDWF	**f,d**	Add W and f	1	0001 11df ffff		C,DC,Z	1,2,4
ANDWF	**f,d**	AND W with f	1	0001 01df ffff		Z	2,4
CLRF	**f**	Clear f	1	0000 011f ffff		Z	4
CLRW	**–**	Clear W	1	0000 0100 0000		Z	
COMF	**f, d**	Complement f	1	0010 01df ffff		Z	
DECF	**f, d**	Decrement f	1	0000 11df ffff		Z	2,4
DECFSZ	**f, d**	Decrement f, Skip if 0	1(2)	0010 11df ffff		None	2,4
INCF	**f, d**	Increment f	1	0010 10df ffff		Z	2,4
INCFSZ	**f, d**	Increment f, Skip if 0	1(2)	0011 11df ffff		None	2,4
IORWF	**f, d**	Inclusive OR W with f	1	0001 00df ffff		Z	2,4
MOVF	**f, d**	Move f	1	0010 00df ffff		Z	2,4
MOVWF	**f**	Move W to f	1	0000 001f ffff		None	1,4
NOP	**–**	No Operation	1	0000 0000 0000		None	
RLF	**f, d**	Rotate left f through Carry	1	0011 01df ffff		C	2,4
RRF	**f, d**	Rotate right f through Carry	1	0011 00df ffff		C	2,4
SUBWF	**f, d**	Subtract W from f	1	0000 10df ffff		C,DC,Z	1,2,4
SWAPF	**f, d**	Swap f	1	0011 10df ffff		None	2,4
XORWF	**f, d**	Exclusive OR W with f	1	0001 10df ffff		Z	2,4
BIT-ORIENTED FILE REGISTER OPERATIONS							
BCF	**f, b**	Bit Clear f	1	0100 bbbf ffff		None	2,4
BSF	**f, b**	Bit Set f	1	0101 bbbf ffff		None	2,4
BTFSC	**f, b**	Bit Test f, Skip if Clear	1 (2)	0110 bbbf ffff		None	
BTFSS	**f, b**	Bit Test f, Skip if Set	1 (2)	0111 bbbf ffff		None	
LITERAL AND CONTROL OPERATIONS							
ANDLW	**k**	AND literal with W	1	1110 kkkk kkkk		Z	
CALL	**k**	Call subroutine	2	1001 kkkk kkkk		None	1
CLRWDT	**k**	Clear Watchdog Timer	1	0000 0000 0100		$\overline{TO}$, $\overline{PD}$	
GOTO	**k**	Unconditional branch	2	101k kkkk kkkk		None	
IORLW	**k**	Inclusive OR Literal with W	1	1101 kkkk kkkk		Z	
MOVLW	**k**	Move Literal to W	1	1100 kkkk kkkk		None	
OPTION	**–**	Load OPTION register	1	0000 0000 0010		None	
RETLW	**k**	Return, place Literal in W	2	1000 kkkk kkkk		None	
SLEEP	**–**	Go into standby mode	1	0000 0000 0011		$\overline{TO}$, $\overline{PD}$	
TRIS	**f**	Load TRIS register	1	0000 0000 0fff		None	3
XORLW	**k**	Exclusive OR Literal to W	1	1111 kkkk kkkk		Z	

Note 1: The 9th bit of the program counter will be forced to a '0' by any instruction that writes to the PC except for GOTO. (Section 4.6)

2: When an I/O register is modified as a function of itself (e.g. `MOVF GPIO, 1`), the value used will be that value present on the pins themselves. For example, if the data latch is '1' for a pin configured as input and is driven low by an external device, the data will be written back with a '0'.

3: The instruction `TRIS f`, where f = 6 causes the contents of the W register to be written to the tristate latches of GPIO. A '1' forces the pin to a hi-impedance state and disables the output buffers.

4: If this instruction is executed on the TMR0 register (and, where applicable, d = 1), the prescaler will be cleared (if assigned to TMR0).

OPTION **Load OPTION Register**

Syntax: [*label*] OPTION

Operands: None

Operation: (W) → OPTION

Status Affected: None

Encoding:

0000	0000	0010

Description: The content of the W register is loaded into the OPTION register.

Words: 1

Cycles: 1

Example

```
OPTION
```

Before Instruction
W = 0x07

After Instruction
OPTION = 0x07

RETLW **Return with Literal in W**

Syntax: [*label*] RETLW k

Operands: 0 ≤ k ≤ 255

Operation: k → (W);
TOS → PC

Status Affected: None

Encoding:

1000	kkkk	kkkk

Description: The W register is loaded with the eight bit literal 'k'. The program counter is loaded from the top of the stack (the return address). This is a two cycle instruction.

Words: 1

Cycles: 2

Example:

```
CALL TABLE ;W contains
           ;table offset
           ;value.
•          ;W now has table
•          ;value.
•
TABLE      ADDWF PC   ;W = offset
           RETLW k1   ;Begin table
           RETLW k2   ;
           •
           •
           •
           RETLW kn   ; End of table
```

Before Instruction
W = 0x07

After Instruction
W = value of k8

RLF **Rotate Left f through Carry**

Syntax: [*label*] RLF f,d

Operands: 0 ≤ f ≤ 31
d ∈ [0,1]

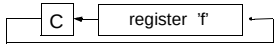
Operation: See description below

Status Affected: C

Encoding:

0011	01df	ffff

Description: The contents of register 'f' are rotated one bit to the left through the Carry Flag. If 'd' is 0 the result is placed in the W register. If 'd' is 1 the result is stored back in register 'f'.



Words: 1

Cycles: 1

Example:

```
RLF     REG1,0
```

Before Instruction
```
REG1    =   1110 0110
C       =   0
```

After Instruction
```
REG1    =   1110 0110
W       =   1100 1100
C       =   1
```

RRF **Rotate Right f through Carry**

Syntax: [*label*] RRF f,d

Operands: 0 ≤ f ≤ 31
d ∈ [0,1]

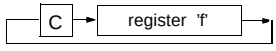
Operation: See description below

Status Affected: C

Encoding:

0011	00df	ffff

Description: The contents of register 'f' are rotated one bit to the right through the Carry Flag. If 'd' is 0 the result is placed in the W register. If 'd' is 1 the result is placed back in register 'f'.



Words: 1

Cycles: 1

Example:

```
RRF     REG1,0
```

Before Instruction
```
REG1    =   1110 0110
C       =   0
```

After Instruction
```
REG1    =   1110 0110
W       =   0111 0011
C       =   0
```

SWAPF **Swap Nibbles in f**

Syntax: [*label*] SWAPF f,d

Operands: $0 \le f \le 31$
$d \in [0,1]$

Operation: (f<3:0>) → (dest<7:4>);
(f<7:4>) → (dest<3:0>)

Status Affected: None

Encoding:

0011	10df	ffff

Description: The upper and lower nibbles of register 'f' are exchanged. If 'd' is 0 the result is placed in W register. If 'd' is 1 the result is placed in register 'f'.

Words: 1

Cycles: 1

Example
```
SWAPF   REG1,  0
```
Before Instruction
REG1 = 0xA5

After Instruction
REG1 = 0xA5
W = 0X5A

TRIS **Load TRIS Register**

Syntax: [*label*] TRIS f

Operands: f = 6

Operation: (W) → TRIS register f

Status Affected: None

Encoding:

0000	0000	0fff

Description: TRIS register 'f' (f = 6) is loaded with the contents of the W register

Words: 1

Cycles: 1

Example
```
TRIS    GPIO
```
Before Instruction
W = 0XA5

After Instruction
TRIS = 0XA5

Note: f = 6 for PIC12C5XX only.

XORLW **Exclusive OR literal with W**

Syntax: [*label*] XORLW k

Operands: $0 \le k \le 255$

Operation: (W) .XOR. k → (W)

Status Affected: Z

Encoding:

1111	kkkk	kkkk

Description: The contents of the W register are XOR'ed with the eight bit literal 'k'. The result is placed in the W register.

Words: 1

Cycles: 1

Example
```
XORLW  0xAF
```
Before Instruction
W = 0xB5

After Instruction
W = 0x1A

XORWF **Exclusive OR W with f**

Syntax: [*label*] XORWF f,d

Operands: $0 \le f \le 31$
$d \in [0,1]$

Operation: (W) .XOR. (f) → (dest)

Status Affected: Z

Encoding:

0001	10df	ffff

Description: Exclusive OR the contents of the W register with register 'f'. If 'd' is 0 the result is stored in the W register. If 'd' is 1 the result is stored back in register 'f'.

Words: 1

Cycles: 1

Example
```
XORWF  REG,1
```
Before Instruction
REG = 0xAF
W = 0xB5

After Instruction
REG = 0x1A
W = 0xB5

NOTES:

10.6 SIMICE Entry-Level Hardware Simulator

SIMICE is an entry-level hardware development system designed to operate in a PC-based environment with Microchip's simulator MPLAB™-SIM. Both SIMICE and MPLAB-SIM run under Microchip Technology's MPLAB Integrated Development Environment (IDE) software. Specifically, SIMICE provides hardware simulation for Microchip's PIC12C5XX, PIC12CE5XX, and PIC16C5X families of PICmicro® 8-bit microcontrollers. SIMICE works in conjunction with MPLAB-SIM to provide non-real-time I/O port emulation. SIMICE enables a developer to run simulator code for driving the target system. In addition, the target system can provide input to the simulator code. This capability allows for simple and interactive debugging without having to manually generate MPLAB-SIM stimulus files. SIMICE is a valuable debugging tool for entry-level system development.

10.7 PICDEM-1 Low-Cost PICmicro® Demonstration Board

The PICDEM-1 is a simple board which demonstrates the capabilities of several of Microchip's microcontrollers. The microcontrollers supported are: PIC16C5X (PIC16C54 to PIC16C58A), PIC16C61, PIC16C62X, PIC16C71, PIC16C8X, PIC17C42, PIC17C43 and PIC17C44. All necessary hardware and software is included to run basic demo programs. The users can program the sample microcontrollers provided with the PICDEM-1 board, on a PRO MATE II or PICSTART-Plus programmer, and easily test firmware. The user can also connect the PICDEM-1 board to the MPLAB-ICE emulator and download the firmware to the emulator for testing. Additional prototype area is available for the user to build some additional hardware and connect it to the microcontroller socket(s). Some of the features include an RS-232 interface, a potentiometer for simulated analog input, push-button switches and eight LEDs connected to PORTB.

10.8 PICDEM-2 Low-Cost PIC16CXX Demonstration Board

The PICDEM-2 is a simple demonstration board that supports the PIC16C62, PIC16C64, PIC16C65, PIC16C73 and PIC16C74 microcontrollers. All the necessary hardware and software is included to run the basic demonstration programs. The user can program the sample microcontrollers provided with the PICDEM-2 board, on a PRO MATE II programmer or PICSTART-Plus, and easily test firmware. The MPLAB-ICE emulator may also be used with the PICDEM-2 board to test firmware. Additional prototype area has been provided to the user for adding additional hardware and connecting it to the microcontroller socket(s). Some of the features include a RS-232 interface, push-button switches, a potentiometer for simulated analog input, a Serial EEPROM to demonstrate usage of the I^2C bus and separate headers for connection to an LCD module and a keypad.

10.9 PICDEM-3 Low-Cost PIC16CXXX Demonstration Board

The PICDEM-3 is a simple demonstration board that supports the PIC16C923 and PIC16C924 in the PLCC package. It will also support future 44-pin PLCC microcontrollers with a LCD Module. All the necessary hardware and software is included to run the basic demonstration programs. The user can program the sample microcontrollers provided with the PICDEM-3 board, on a PRO MATE II programmer or PICSTART Plus with an adapter socket, and easily test firmware. The MPLAB-ICE emulator may also be used with the PICDEM-3 board to test firmware. Additional prototype area has been provided to the user for adding hardware and connecting it to the microcontroller socket(s). Some of the features include an RS-232 interface, push-button switches, a potentiometer for simulated analog input, a thermistor and separate headers for connection to an external LCD module and a keypad. Also provided on the PICDEM-3 board is an LCD panel, with 4 commons and 12 segments, that is capable of displaying time, temperature and day of the week. The PICDEM-3 provides an additional RS-232 interface and Windows 3.1 software for showing the demultiplexed LCD signals on a PC. A simple serial interface allows the user to construct a hardware demultiplexer for the LCD signals.

TABLE 11-3: CALIBRATED INTERNAL RC FREQUENCIES - PIC12C508/C509

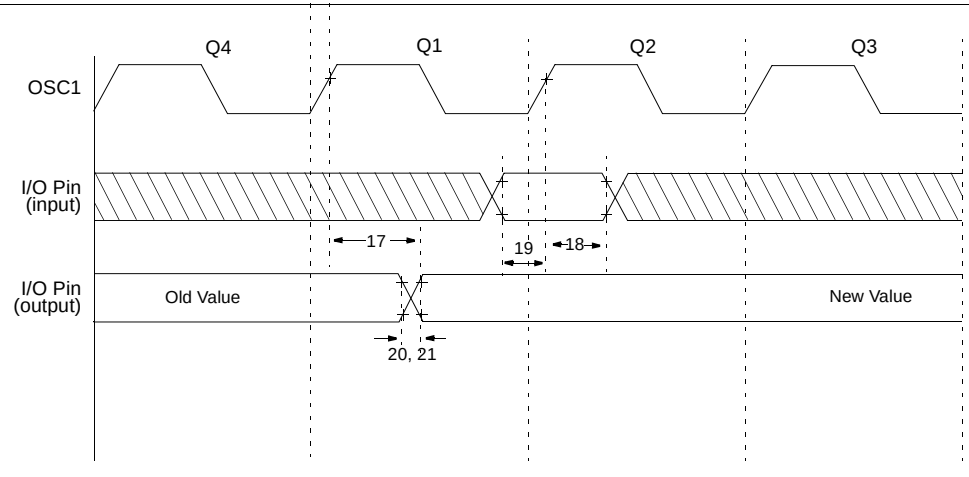
AC Characteristics	Standard Operating Conditions (unless otherwise specified) Operating Temperature 0°C ≤ TA ≤ +70°C (commercial), –40°C ≤ TA ≤ +85°C (industrial), –40°C ≤ TA ≤ +125°C (extended) Operating Voltage VDD range is described in Section 10.1

Parameter No.	Sym	Characteristic	Min*	Typ(1)	Max*	Units	Conditions
		Internal Calibrated RC Frequency	3.58	4.00	4.32	MHz	VDD = 5.0V
		Internal Calibrated RC Frequency	3.50	—	4.26	MHz	VDD = 2.5V

* These parameters are characterized but not tested.

Note 1: Data in the Typical ("Typ") column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

FIGURE 11-3: I/O TIMING - PIC12C508/C509



Note: All tests must be done with specified capacitive loads (see data sheet) 50 pF on I/O pins and CLKOUT.

NOTES:

13.1 DC CHARACTERISTICS: PIC12C508A/509A (Commercial, Industrial, Extended) PIC12CE518/519 (Commercial, Industrial, Extended) PIC12CR509A (Commercial, Industrial, Extended)

DC Characteristics Power Supply Pins			Standard Operating Conditions (unless otherwise specified) Operating Temperature 0°C ≤ TA ≤ +70°C (commercial) –40°C ≤ TA ≤ +85°C (industrial) –40°C ≤ TA ≤ +125°C (extended)				
Parm No.	**Characteristic**	**Sym**	**Min**	**Typ(1)**	**Max**	**Units**	**Conditions**
D001	**Supply Voltage**	VDD	3.0		5.5	V	FOSC = DC to 4 MHz (Commercial/ Industrial, Extended)
D002	**RAM Data Retention Voltage(2)**	VDR		1.5*		V	Device in SLEEP mode
D003	**VDD Start Voltage to ensure Power-on Reset**	VPOR		VSS		V	See section on Power-on Reset for details
D004	**VDD Rise Rate to ensure Power-on Reset**	SVDD	0.05*			V/ms	See section on Power-on Reset for details
D010	**Supply Current(3)**	IDD	—	0.8	1.4	mA	XT and EXTRC options (Note 4) FOSC = 4 MHz, VDD = 5.5V
D010C			—	0.8	1.4	mA	INTRC Option FOSC = 4 MHz, VDD = 5.5V
D010A			—	19	27	µA	LP OPTION, Commercial Temperature FOSC = 32 kHz, VDD = 3.0V, WDT disabled
			—	19	35	µA	LP OPTION, Industrial Temperature FOSC = 32 kHz, VDD = 3.0V, WDT disabled
			—	30	55	µA	LP OPTION, Extended Temperature FOSC = 32 kHz, VDD = 3.0V, WDT disabled
D020	**Power-Down Current (5)**	IPD	—	0.25	4	µA	VDD = 3.0V, Commercial WDT disabled
D021			—	0.25	5	µA	VDD = 3.0V, Industrial WDT disabled
D021B			—	2	12	µA	VDD = 3.0V, Extended WDT disabled
D022	**Power-Down Current**	ΔIWDT	—	2.2	5	µA	VDD = 3.0V, Commercial
			—	2.2	6	µA	VDD = 3.0V, Industrial
			—	4	11	µA	VDD = 3.0V, Extended
	Supply Current (3) During read/write to EEPROM peripheral	ΔIEE	—	0.1	0.2	mA	FOSC = 4 MHz, Vdd = 5.5V, SCL = 400kHz

* These parameters are characterized but not tested.

Note 1: Data in the Typical ("Typ") column is based on characterization results at 25°C. This data is for design guidance only and is not tested.

2: This is the limit to which VDD can be lowered in SLEEP mode without losing RAM data.

3: The supply current is mainly a function of the operating voltage and frequency. Other factors such as bus loading, oscillator type, bus rate, internal code execution pattern, and temperature also have an impact on the current consumption.

a) The test conditions for all IDD measurements in active operation mode are: OSC1 = external square wave, from rail-to-rail; all I/O pins tristated, pulled to VSS, T0CKI = VDD, $\overline{MCLR}$ = VDD; WDT enabled/disabled as specified.

b) For standby current measurements, the conditions are the same, except that the device is in SLEEP mode.

4: Does not include current through Rext. The current through the resistor can be estimated by the formula: IR = VDD/2Rext (mA) with Rext in kOhm.

5: The power down current in SLEEP mode does not depend on the oscillator type. Power down current is measured with the part in SLEEP mode, with all I/O pins in hi-impedance state and tied to VDD or VSS.

TABLE 13-1: PULL-UP RESISTOR RANGES* - PIC12C508A, PIC12C509A, PIC12CR509A, PIC12CE518, PIC12CE519, PIC12LC508A, PIC12LC509A, PIC12LCR509A, PIC12LCE518 and PIC12LCE519

VDD (Volts)	Temperature (°C)	Min	Typ	Max	Units
GP0/GP1					
2.5	–40	38K	42K	63K	Ω
	25	42K	48K	63K	Ω
	85	42K	49K	63K	Ω
	125	50K	55K	63K	Ω
5.5	–40	15K	17K	20K	Ω
	25	18K	20K	23K	Ω
	85	19K	22K	25K	Ω
	125	22K	24K	28K	Ω
GP3					
2.5	–40	285K	346K	417K	Ω
	25	343K	414K	532K	Ω
	85	368K	457K	532K	Ω
	125	431K	504K	593K	Ω
5.5	–40	247K	292K	360K	Ω
	25	288K	341K	437K	Ω
	85	306K	371K	448K	Ω
	125	351K	407K	500K	Ω

***** These parameters are characterized but not tested.

TABLE 13-8: EEPROM MEMORY BUS TIMING REQUIREMENTS - PIC12CE5XX ONLY.

AC Characteristics	Standard Operating Conditions (unless otherwise specified) Operating Temperature 0°C ≤ TA ≤ +70°C, Vcc = 3.0V to 5.5V (commercial) –40°C ≤ TA ≤ +85°C, Vcc = 3.0V to 5.5V (industrial) –40°C ≤ TA ≤ +125°C, Vcc = 4.5V to 5.5V (extended) Operating Voltage VDD range is described in Section 13.1				
Parameter	**Symbol**	**Min**	**Max**	**Units**	**Conditions**
Clock frequency	FCLK	— — —	100 100 400	kHz	4.5V ≤ Vcc ≤ 5.5V (E Temp range) 3.0V ≤ Vcc ≤ 4.5V 4.5V ≤ Vcc ≤ 5.5V
Clock high time	THIGH	4000 4000 600	— — —	ns	4.5V ≤ Vcc ≤ 5.5V (E Temp range) 3.0V ≤ Vcc ≤ 4.5V 4.5V ≤ Vcc ≤ 5.5V
Clock low time	TLOW	4700 4700 1300	— — —	ns	4.5V ≤ Vcc ≤ 5.5V (E Temp range) 3.0V ≤ Vcc ≤ 4.5V 4.5V ≤ Vcc ≤ 5.5V
SDA and SCL rise time (Note 1)	TR	— — —	1000 1000 300	ns	4.5V ≤ Vcc ≤ 5.5V (E Temp range) 3.0V ≤ Vcc ≤ 4.5V 4.5V ≤ Vcc ≤ 5.5V
SDA and SCL fall time	TF	—	300	ns	(Note 1)
START condition hold time	THD:STA	4000 4000 600	— — —	ns	4.5V ≤ Vcc ≤ 5.5V (E Temp range) 3.0V ≤ Vcc ≤ 4.5V 4.5V ≤ Vcc ≤ 5.5V
START condition setup time	TSU:STA	4700 4700 600	— — —	ns	4.5V ≤ Vcc ≤ 5.5V (E Temp range) 3.0V ≤ Vcc ≤ 4.5V 4.5V ≤ Vcc ≤ 5.5V
Data input hold time	THD:DAT	0	—	ns	(Note 2)
Data input setup time	TSU:DAT	250 250 100	— — —	ns	4.5V ≤ Vcc ≤ 5.5V (E Temp range) 3.0V ≤ Vcc ≤ 4.5V 4.5V ≤ Vcc ≤ 5.5V
STOP condition setup time	TSU:STO	4000 4000 600	— — —	ns	4.5V ≤ Vcc ≤ 5.5V (E Temp range) 3.0V ≤ Vcc ≤ 4.5V 4.5V ≤ Vcc ≤ 5.5V
Output valid from clock (Note 2)	TAA	— — —	3500 3500 900	ns	4.5V ≤ Vcc ≤ 5.5V (E Temp range) 3.0V ≤ Vcc ≤ 4.5V 4.5V ≤ Vcc ≤ 5.5V
Bus free time: Time the bus must be free before a new transmission can start	TBUF	4700 4700 1300	— — —	ns	4.5V ≤ Vcc ≤ 5.5V (E Temp range) 3.0V ≤ Vcc ≤ 4.5V 4.5V ≤ Vcc ≤ 5.5V
Output fall time from VIH minimum to VIL maximum	TOF	20+0.1 CB	250	ns	(Note 1), CB ≤ 100 pF
Input filter spike suppression (SDA and SCL pins)	TSP	—	50	ns	(Notes 1, 3)
Write cycle time	TWC	—	4	ms	
Endurance		1M	—	cycles	25°C, VCC = 5.0V, Block Mode (Note 4)

Note 1: Not 100% tested. CB = total capacitance of one bus line in pF.

2: As a transmitter, the device must provide an internal minimum delay time to bridge the undefined region (minimum 300 ns) of the falling edge of SCL to avoid unintended generation of START or STOP conditions.

3: The combined TSP and VHYS specifications are due to new Schmitt trigger inputs which provide improved noise spike suppression. This eliminates the need for a TI specification for standard operation.

4: This parameter is not tested but guaranteed by characterization. For endurance estimates in a specific application, please consult the Total Endurance Model which can be obtained on Microchip's website.

NOTES:

TABLE 14-1: DYNAMIC IDD (TYPICAL) - WDT ENABLED, 25°C

Oscillator	Frequency	VDD =3.0V	VDD = 5.5V
External RC	4 MHz	240 µA*	800 µA*
Internal RC	4 MHz	320 µA	800 µA
XT	4 MHz	300 µA	800 µA
LP	32 KHz	19 µA	50 µA

*Does not include current through external R&C.

FIGURE 14-3: TYPICAL IDD VS. VDD (WDT DIS, 25°C, FREQUENCY = 4MHz)

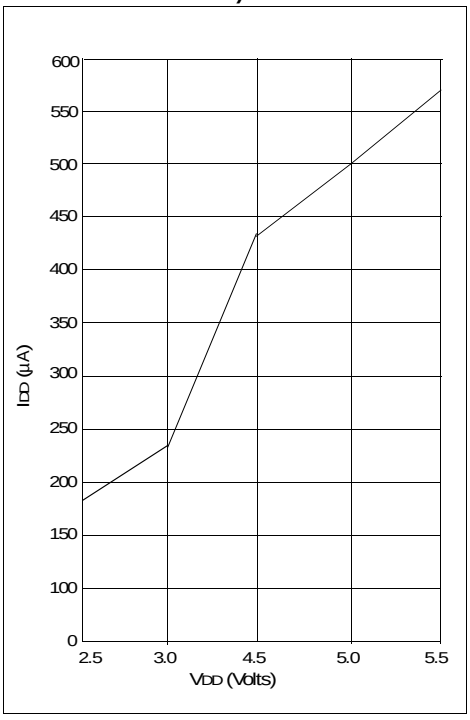


FIGURE 14-4: TYPICAL IDD VS. FREQUENCY (WDT DIS, 25°C, VDD = 5.5V)

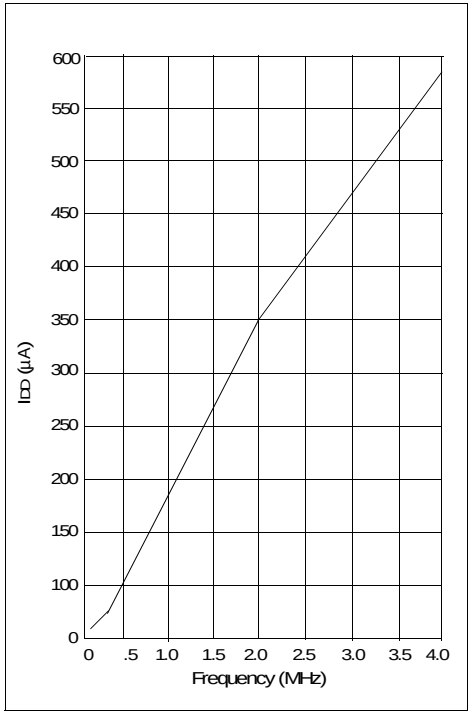


FIGURE 14-13: TYPICAL IPD VS. VDD, WATCHDOG DISABLED (25°C)

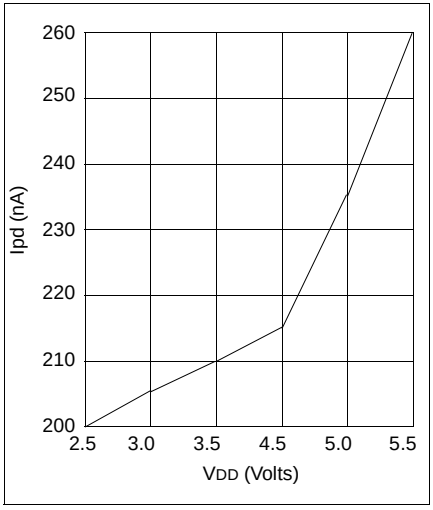
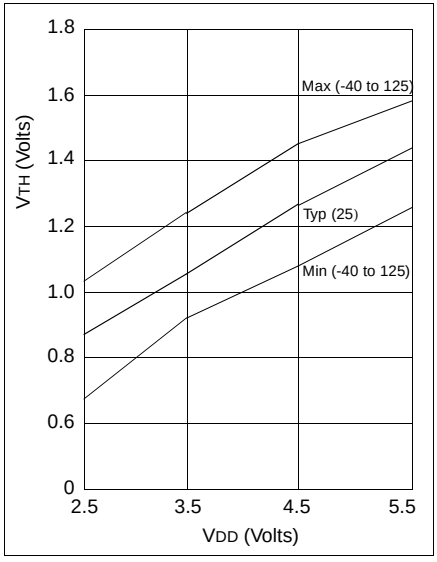


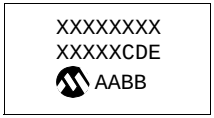
FIGURE 14-14: VTH (INPUT THRESHOLD VOLTAGE) OF GPIO PINS VS. VDD



15.0 PACKAGING INFORMATION

15.1 Package Marking Information

8-Lead PDIP (300 mil)

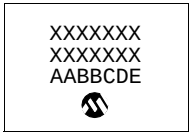


Example

8-Lead SOIC (150 mil)

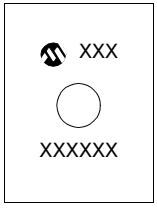
Example

8-Lead SOIC (208 mil)

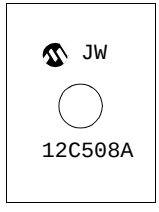


Example

8-Lead Windowed Ceramic Side Brazed (300 mil)



Example



Legend:	MM...M	Microchip part number information
	XX...X	Customer specific information*
	AA	Year code (last 2 digits of calendar year)
	BB	Week code (week of January 1 is week ‘01’)
	C	Facility code of the plant at which wafer is manufactured O = Outside Vendor C = 5” Line S = 6” Line H = 8” Line
	D	Mask revision number
	E	Assembly code of the plant or country of origin in which part was assembled
Note:		In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line thus limiting the number of available characters for customer specific information.

***** Standard OTP marking consists of Microchip part number, year code, week code, facility code, mask rev#, and assembly code. For OTP marking beyond this, certain price adders apply. Please check with your Microchip Sales Office. For QTP devices, any special marking adders are included in QTP price.

PIC12C5XX Product Identification System

PART NO. -XX X /XX XXX

Pattern:	Special Requirements	
Package:	SN	= 150 mil SOIC
	SM	= 208 mil SOIC
	P	= 300 mil PDIP
	JW	= 300 mil Windowed Ceramic Side Brazed
Temperature Range:	-	= 0°C to +70°C
	I	= -40°C to +85°C
	E	= -40°C to +125°C
Frequency Range:	04	= 4 MHz
Device	PIC12C508 PIC12C509 PIC12C508T (Tape & reel for SOIC only) PIC12C509T (Tape & reel for SOIC only) PIC12C508A PIC12C509A PIC12C508AT (Tape & reel for SOIC only) PIC12C509AT (Tape & reel for SOIC only) PIC12LC508A PIC12LC509A PIC12LC508AT (Tape & reel for SOIC only) PIC12LC509AT (Tape & reel for SOIC only) PIC12CR509A PIC12CR509AT (Tape & reel for SOIC only) PIC12LCR509A PIC12LCR509AT (Tape & reel for SOIC only) PIC12CE518 PIC12CE518T (Tape & reel for SOIC only) PIC12CE519 PIC12CE519T (Tape & reel for SOIC only) PIC12LCE518 PIC12LCE518T (Tape & reel for SOIC only) PIC12LCE519 PIC12LCE519T (Tape & reel for SOIC only)	

Examples

a) PIC12C508A-04/P Commercial Temp., PDIP Package, 4 MHz, normal V_{DD} limits

b) PIC12C508A-04I/SM Industrial Temp., SOIC package, 4 MHz, normal V_{DD} limits

c) PIC12C509-04I/P Industrial Temp., PDIP package, 4 MHz, normal V_{DD} limits

Please contact your local sales office for exact ordering procedures.

Sales and Support:

Data Sheets

Products supported by a preliminary Data Sheet may have an errata sheet describing minor operational differences and recommended workarounds. To determine if an errata sheet exists for a particular device, please contact one of the following:

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2. The Microchip Corporate Literature Center U.S. FAX: (602) 786-7277
3. The Microchip Worldwide Site (www.microchip.com)

Please specify which device, revision of silicon and Data Sheet (include Literature #) you are using.

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